## Please REPLACE the paragraph beginning at page 15, line 23, as follows:

KZ

In this way, according to the present invention, the power consumed in the address drive IC (capacitive-load driving circuit) 3 can be reduced. That is, though the power consumption as a whole remains the same, a portion of the power that would have been consumed in the address drive IC 3 in the prior art is consumed by the power distributing means 2; this construction serves to simplify the heat sinking structure of the address drive IC 3, and achieves a reduction in circuit cost.

## Please REPLACE the paragraph beginning at page 16, line 18, as follows:



Figure 4 is a block diagram showing a first embodiment of the capacitive-load driving circuit according to the present invention. In Figure 4, reference numeral 1 is a driving power supply source, 21 is a power distributing means, or circuit, 3 is an address drive IC, 4 is a reference potential point (ground point), 5 is a load capacitor, 6 and 7 are driving devices, 8 and 9 are a power supply terminal and a reference potential terminal (ground terminal), respectively, of the address drive IC, and 10 is an output terminal of the address drive IC.

## Please REPLACE the paragraph beginning at page 16, line 29, as follows:



As shown in Figure 4, in the first embodiment, the power distributing means, or circuit, 21 is inserted between the driving power supply source 1 and the high-level voltage supply terminal 8 of the address drive IC 3; this power distributing means is constructed as a resistive impedance (resistive element) 21 whose value is higher than about one-tenth of the resistive impedance that the driving device 6 provides at the time of conduction (the resistive component of the conducting impedance). According to the first embodiment, the power consumption of the driving circuit 3 can be reduced by distributing to the resistive element 21 about one-tenth or more of the power consumed in the driving device 6 during load driving.

Please REPLACE the paragraph beginning at page 37, line 20, as follows:



As shown in Figure 27, the 17th embodiment, the present invention is applied to the address drive IC 3 for driving, for example, the number, d, address lines (A1 to Ad) in a plasma